



Material Content Data Sheet



Sales Product Name		ICE3BR1765JZ		Issued		29. August 2013		
MA#		MA001099514						
Package		PG-DIP-7-4		Weight*		652.60 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.344	0.51	0.51	5124	5124
leadframe	inorganic material	phosphorus	7723-14-0	0.049	0.01		74	
	non noble metal	zinc	7440-66-6	0.194	0.03		298	
	non noble metal	iron	7439-89-6	3.884	0.60		5952	
wire	non noble metal	copper	7440-50-8	157.726	24.17	24.81	241690	248014
	noble metal	gold	7440-57-5	0.293	0.04	0.04	449	449
	encapsulation	organic material	carbon black	1333-86-4	1.431	0.22		2193
encapsulation	plastics	epoxy resin	-	46.270	7.09		70902	
	inorganic material	silicondioxide	60676-86-0	429.311	65.79	73.10	657850	730945
leadfinish	non noble metal	tin	7440-31-5	6.460	0.99	0.99	9898	9898
plating	noble metal	silver	7440-22-4	1.911	0.29	0.29	2928	2928
glue	plastics	epoxy resin	-	0.259	0.04		396	
	noble metal	silver	7440-22-4	1.466	0.22	0.26	2246	2642
*deviation	< 10%					Sum in total:	100,00	1000000

Important Remarks:

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